

PMEG100T080ELPE-Q

100 V, 8 A low leakage current Trench MEGA Schottky barrier rectifier

8 October 2021

Product data sheet

1. General description

Trench Maximum Efficiency General Application (MEGA) Schottky barrier rectifier encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Low forward voltage
- Low Q_{rr} and low I_{RM}
- · Low leakage current
- · High power capability due to clip-bonding technology
- Small and flat lead SMD power plastic package
- · Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- High efficiency DC-to-DC conversion
- · Automotive LED lighting
- Switch mode power supply
- Freewheeling application
- Reverse polarity protection
- OR-ing

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; T _{sp} ≤ 162 °C		-	-	8	Α
V_R	reverse voltage	T _j = 25 °C		-	-	100	V
V _F	forward voltage	I _F = 8 A; pulsed; T _j = 25 °C	[1]	-	730	810	mV
I _R	reverse current	V _R = 100 V; pulsed; T _j = 25 °C	[1]	-	0.8	4	μΑ
		V_R = 100 V; pulsed; T_j = 125 °C	[1]	-	1.1	6	mA

^[1] Very short pulse, in order to maintain a stable junction temperature.



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A	anode	5	
2	A	anode		K F
3	K	cathode	2	aaa-009063
			CFP15B (SOT1289B)	

6. Ordering information

Table 3. Ordering information

Type number	Package						
	Name	Description	Version				
PMEG100T080ELPE-Q		plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body	SOT1289B				

7. Marking

Table 4. Marking codes

Marking code
100T L08E

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _R	reverse voltage	T _j = 25 °C		-	100	V
I _F	forward current	δ = 1; T _{sp} ≤ 158 °C		-	11.3	А
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; $T_{sp} \le$ 162 °C		-	8	А
I _{FSM}	non-repetitive peak forward current	t_p = 8.3 ms; half sine wave; $T_{j(init)}$ = 25 °C		-	170	А
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1]	-	1.66	W
			[2]	-	2.15	W
Tj	junction temperature			-	175	°C
T _{amb}	ambient temperature			-55	175	°C
T _{stg}	storage temperature			-65	175	°C

^[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

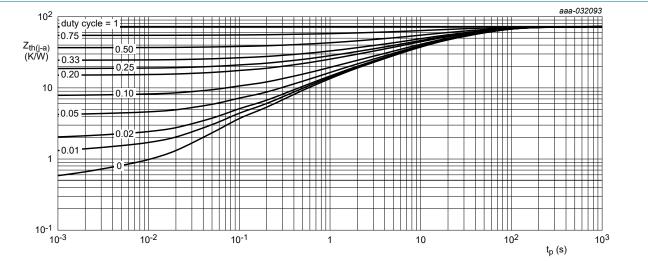
^[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

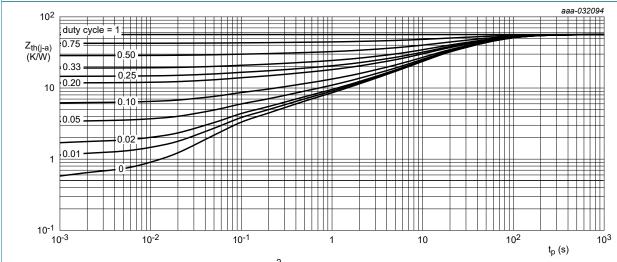
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R _{th(j-a)}	thermal resistance from	in free air	[1] [2]	-	-	90	K/W
juno	unction to ambient		[1] [3]	-	-	70	K/W
R _{th(j-sp)}	thermal resistance from junction to solder point		[4]	-	-	7	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Soldering point of cathode tab.



FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

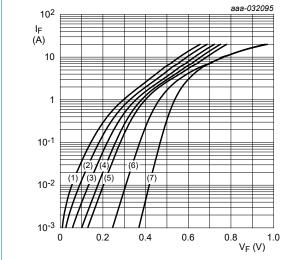
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	I _R = 1 mA; T _j = 25 °C	[1]	100	-	-	V
V _F	forward voltage	I _F = 1 A; pulsed; T _j = 25 °C	[1]	-	465	550	mV
		I _F = 2 A; pulsed; T _j = 25 °C	[1]	-	515	600	mV
		I _F = 3 A; pulsed; T _j = 25 °C	[1]	-	560	630	mV
		I _F = 5 A; pulsed; T _j = 25 °C	[1]	-	635	710	mV
		I _F = 8 A; pulsed; T _j = 25 °C	[1]	-	730	810	mV
		I _F = 8 A; pulsed; T _j = -40 °C	[1]	-	730	820	mV
		I _F = 8 A; pulsed; T _j = 125 °C	[1]	-	610	690	mV
		I _F = 8 A; pulsed; T _j = 150 °C	[1]	-	575	650	mV
I _R	reverse current	V _R = 60 V; pulsed; T _j = 25 °C	[1]	-	0.28	1.5	μΑ
		V _R = 100 V; pulsed; T _j = 25 °C	[1]	-	0.8	4	μΑ
		V _R = 100 V; pulsed; T _j = 125 °C	[1]	-	1.1	6	mA
		V _R = 100 V; pulsed; T _j = 150 °C	[1]	-	4.6	23	mA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _j = 25 °C		-	680	-	pF
		V _R = 10 V; f = 1 MHz; T _j = 25 °C		-	200	-	pF
t _{rr}	reverse recovery time step recovery	$I_F = 0.5 \text{ A}$; $I_R = 0.5 \text{ A}$; $I_{R(meas)} = 0.1 \text{ A}$; $I_{j} = 25 \text{ °C}$		-	19	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 200 \text{ A/}\mu\text{s}; I_F = 6 \text{ A}; V_R = 26 \text{ V};$ $T_j = 25 \text{ °C}$		-	12	-	ns
I _{RM}	peak reverse recovery current			-	1.3	-	Α
Q _{rr}	reverse recovery charge			-	10	-	nC
V_{FRM}	peak forward recovery voltage	$I_F = 0.5 \text{ A}$; $dI_F/dt = 20 \text{ A/µs}$; $T_j = 25 \text{ °C}$		-	420	-	mV

^[1] Very short pulse, in order to maintain a stable junction temperature.



pulsed condition

(1) $T_i = 175 \,^{\circ}C$

 $(2) T_i = 150 °C$

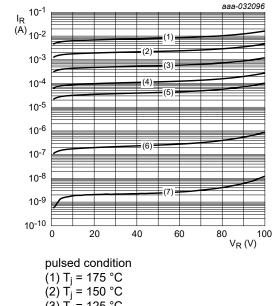
(3) $T_i = 125 °C$

 $(4) T_i = 100 °C$

(5) $T_j = 85 ^{\circ}C$ (6) $T_i = 25 ^{\circ}C$

(7) $T_i = -40$ °C

Fig. 3. Forward current as a function of forward voltage; typical values



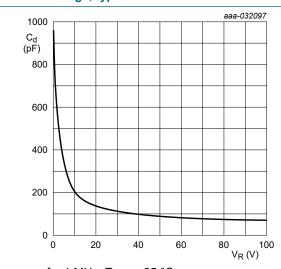
 $(3) T_j = 125 °C$

 $(4) T_j = 100 °C$

(5) $T_j = 85 ^{\circ}C$ (6) $T_i = 25 ^{\circ}C$

 $(7) T_i = -40 ^{\circ}C$

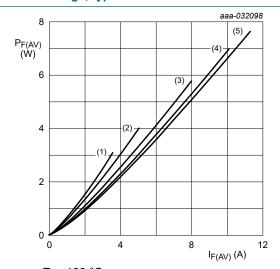
Fig. 4. Reverse current as a function of reverse voltage; typical values



Diode capacitance as a function of reverse

f = 1 MHz; T_{amb} = 25 °C

voltage; typical values



 $T_j = 100 \, ^{\circ}C$

 $(1) \delta = 0.1$

 $(2) \delta = 0.2$

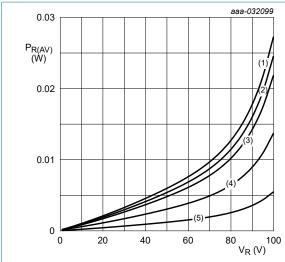
 $(3) \delta = 0.5$

 $(4) \delta = 0.8$

 $(5) \delta = 1; DC$

Fig. 6. Average forward power dissipation as a function of average forward current; typical values

Fig. 5.



T_j = 100 °C

 $(1) \delta = 1$; DC

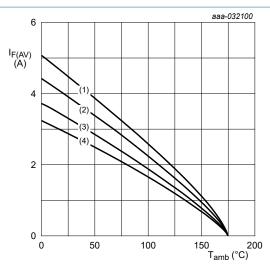
 $(2) \delta = 0.9$

 $(3) \delta = 0.8$

 $(4) \delta = 0.5$

 $(5) \delta = 0.2$

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

T_i = 175 °C

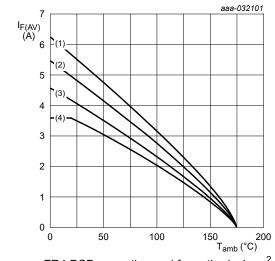
 $(1) \delta = 1; DC$

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm²

T_i = 175 °C

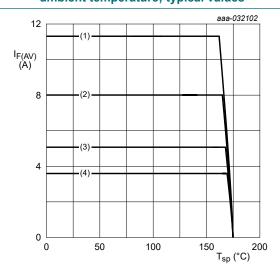
 $(1) \delta = 1$; DC

 $(2) \delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



Tj = 175 °C

(1) δ = 1; DC

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

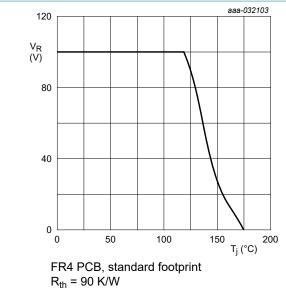
aaa-032104

100 V, 8 A low leakage current Trench MEGA Schottky barrier rectifier

50

100

FR4 PCB, mounting pad for cathode 1 cm²



R_{th} = 90 K/W

Fig. 11. Derated maximum reverse voltage as a function of junction temperature; typical values

R_{th} = 70 K/W

Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values

120

80

40

V_R (V)

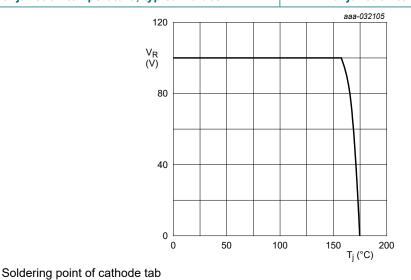


Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

 $R_{th} = 7 \text{ K/W}$

11. Test information

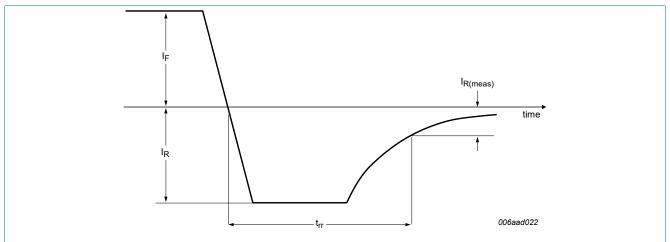


Fig. 14. Reverse recovery definition; step recovery

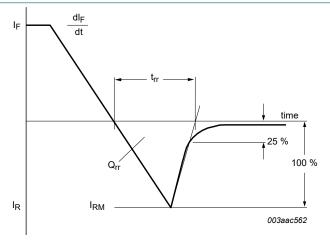


Fig. 15. Reverse recovery definition; ramp recovery

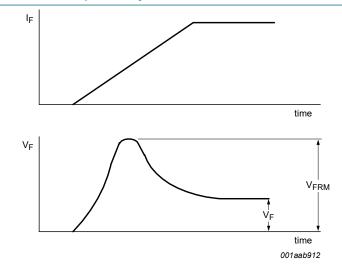
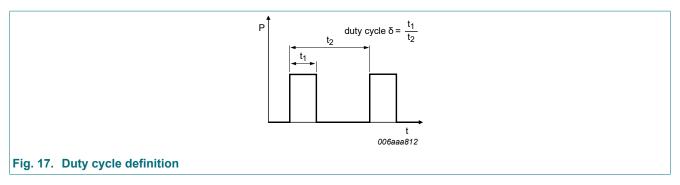


Fig. 16. Forward recovery definition



The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current

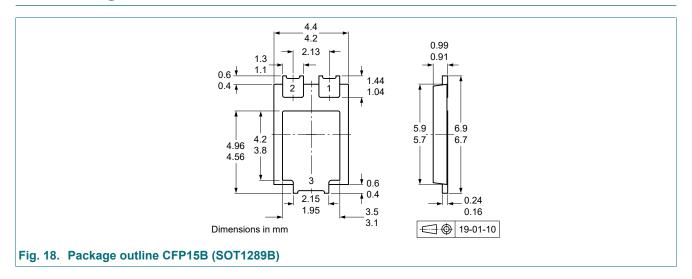
 $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$

with $I_{\mbox{\scriptsize RMS}}$ defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline



13. Soldering

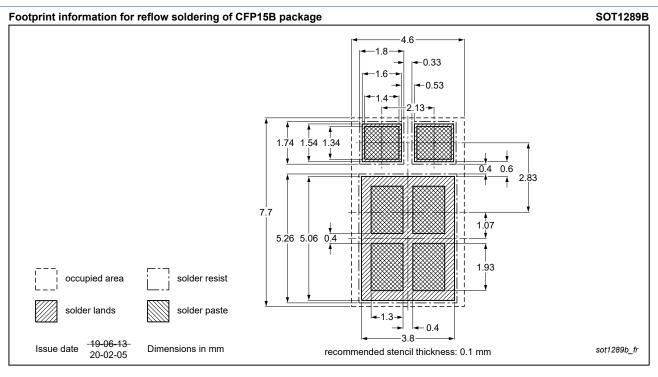


Fig. 19. Reflow soldering footprint for CFP15B (SOT1289B)

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14. Revision history

Table 8. Revision history

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Data sheet ID	Release date	Data sheet status	Change notice	Supersedes				
PMEG100T080ELPE- Q v.3	20211008	Product data sheet	-	PMEG100T080ELPE- Q v.2				
Modifications:	Chapter "Characteris	stics": Typo correction, pa	rameter I _{RM} and Q _{rr}					
PMEG100T080ELPE- Q v.2	20210512	Product data sheet	-	PMEG100T080ELPE- Q v.1				
PMEG100T080ELPE- Q v.1	20210217	Product data sheet	-	-				

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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